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The APA is a NOR-type array (also shown in Fig. 8 of #5,796,142)

My invention is a NOR-type array (also shown in Fig. 7 of my application)

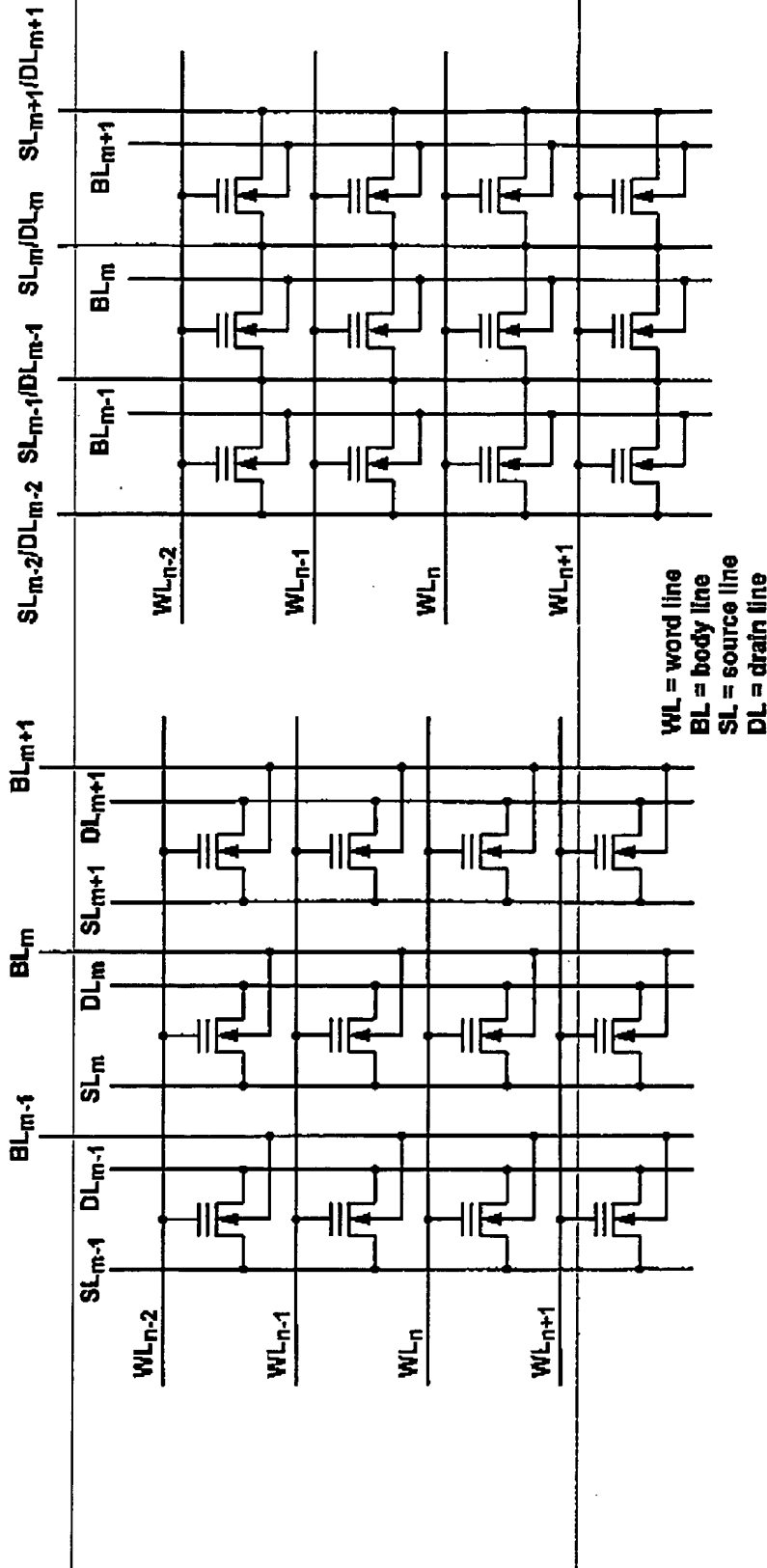


Fig. 2 Both my invention and the APA are contactless NOR-type arrays

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A typical NOR-type Array  
(showing Intel's ETOX Flash)

NAND-type Array

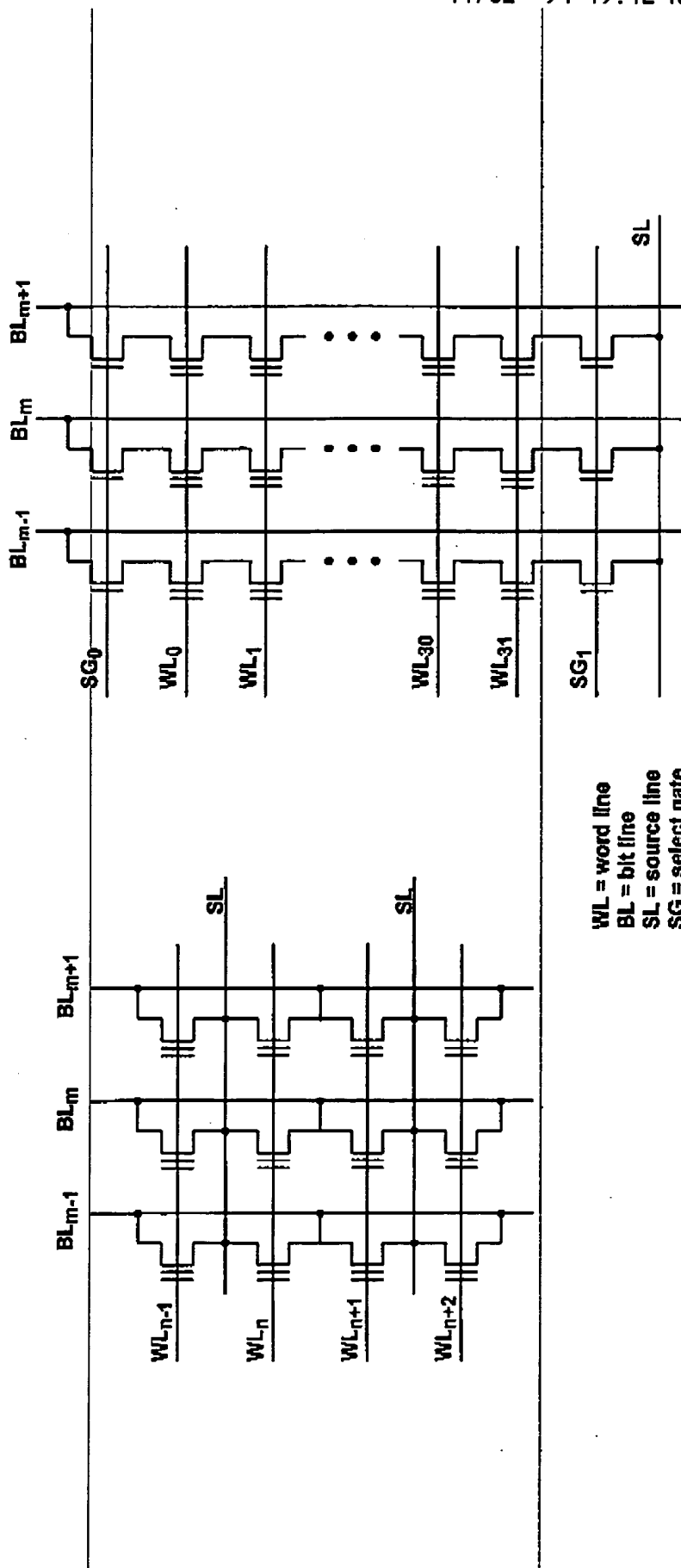


Fig. 1 NOR- and NAND-type Flash Arrays

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What is claimed is:

201. A semiconductor device having an electrically erasable programmable read only memory (EEPROM), comprising
  - a contactless array of EEPROM memory cells disposed in rows and columns and constructed over a silicon-on-insulator wafer, each EEPROM memory cell comprising a drain region, a source region, a gate region, and a body region;
  - a plurality of gate lines each connecting the gate regions of a row of EEPROM memory cells;
  - a plurality of source lines each connecting the source regions and the body regions of a column of EEPROM memory cells; and
  - a plurality of drain lines each connecting the drain regions of a column of EEPROM memory cells;
 wherein the source lines and the drain lines are buried lines; and the source regions and the drain regions of a column of EEPROM memory cells are insulated from the source regions and the drain regions of the adjacent columns of EEPROM memory cells.
212. The semiconductor device of claim 201, further comprising at least a plurality of body lines each connecting the body regions of a column of EEPROM memory cells wherein the source line of a column of EEPROM memory cells is electrically connected to the body line of the same column of EEPROM memory cells.
223. The semiconductor device of claim 212, wherein the source line and the body line of a column of EEPROM memory cells are electrically connected by butting contacts.
74. The semiconductor device of claim 1, wherein at least one source line of a column of EEPROM memory cells is electrically connected to the body line of the same column of EEPROM memory cells.
85. The semiconductor device of claim 74, wherein the source line and the body line are electrically connected by butting contacts.

